## 35K183

#### GaAs N Channel MES FET

For UHF band low-noise amplification

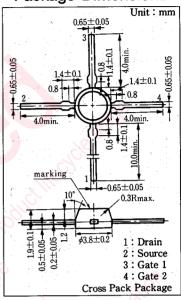
#### **■** Features

- •Low noise figure NF
- •Low small-signal short-circuit input capacitance Ciss
- •Low-voltage operation possible

#### ■ Absolute Maximum Ratings (Ta=25°C)

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Item	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DS</sub>	13	V	
Gate 1-Source Voltage	V <sub>GIS</sub>	-6	v	
Gate 2-Source Voltage	V <sub>G2S</sub>	-6	V	
Drain Current	$I_{\mathbf{D}}$	50	mA	
Gate 1 Current	I <sub>G1</sub>	1	mA	
Gate 2 Current	$I_{G2}$	1	mA (	
Power Dissipation	$P_{D}$	350	mW	
Channel Temperature	T <sub>ch</sub>	135	O'C Q	
Storage Temperature	T <sub>stg</sub>	$-55 \sim +135$	·C	

### ■ Package Dimensions



### ■ Electrical Characteristics (Ta=25°C)

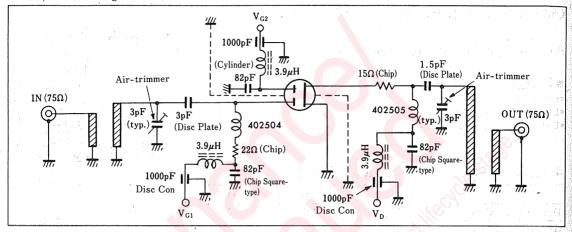
Item	Symbol	Condition	min.	typ.	max.	Unit
Drain Current	I <sub>DSS</sub> *1 *2	$V_{DS} = 5 \text{ V}, \ V_{G1S} = V_{G2S} = 0$	8.5	10	35	mA
Gate 1 Cutoff Current	I <sub>G1SS</sub> *1	$V_{G1S} = -6V, V_{DS} = V_{G2S} = 0$	100	0	-20	μA
Gate 2 Cutoff Current	I <sub>G2SS</sub> *1	$V_{G2S} = -6V, V_{DS} = V_{G1S} = 0$		02	-20	μA
Drain-Source Voltage	V <sub>DSX</sub> *1	$V_{G1S} = -3.5 \text{ V}, V_{G2S} = 0, I_D = 50 \mu\text{A}$	13	1 1		V
Gate 1 Source Cutoff Current	V <sub>GISC</sub> *1	$V_{DS} = 5 \text{ V}, \ V_{G2S} = 0, \ I_{D} = 200 \ \mu\text{A}$	W.,		-6.0	V
Gate 2 Source Cutoff Current	V <sub>G2SC</sub> *1	$V_{DS} = 5 \text{ V}, V_{GIS} = 0, I_{D} = 200 \mu\text{A}$	).		-6.0	V
Mutual Conductance	g <sub>m</sub>	$V_{DS}=5 \text{ V}, V_{G2S}=1.5 \text{ V}, I_{D}=10 \text{ mA}, f=1 \text{ kHz}$	18	23	40-50-5	mS
Drain Current	I <sub>G2D0</sub> *1	V <sub>G2D</sub> =-13V, (Gatel to source:Open)		18 1	50	μA
Input Capacitance	C <sub>iss</sub> *1		:	0.6	2.0	pF
Output Capacitance	Coss *1	$V_{DS} = 5 \text{ V}, V_{G1S} = V_{G2S} = -6.0 \text{ V}, f = 1 \text{ MHz}$		0.35	1.2	pF
Small-Signal Reverse Transfer Capacitance	C <sub>rss</sub> *1			0.02	0.04	pF
Power Gain	PG *3	$V_{DS} = 5 \text{ V}, V_{G2S} = 1.5 \text{ V}, I_D = 10 \text{ mA}, f = 800 \text{MHz}$	13	16	20	dB
Gain Reduction	G <sub>R</sub> *3	$V_{DS} = 5 \text{ V}, V_{AGC} = 1.5 / -3.5 \text{ V}, f = 800 \text{ MHz}$	37	45		dB
Noise Figure	NF *3	$V_{DS} = 5 \text{ V}, V_{G2S} = 1.5 \text{ V}, I_D = 10 \text{ mA}, f = 800 \text{ MHz}$		1.2	2.8	dB
Noise Figure		0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0			·	

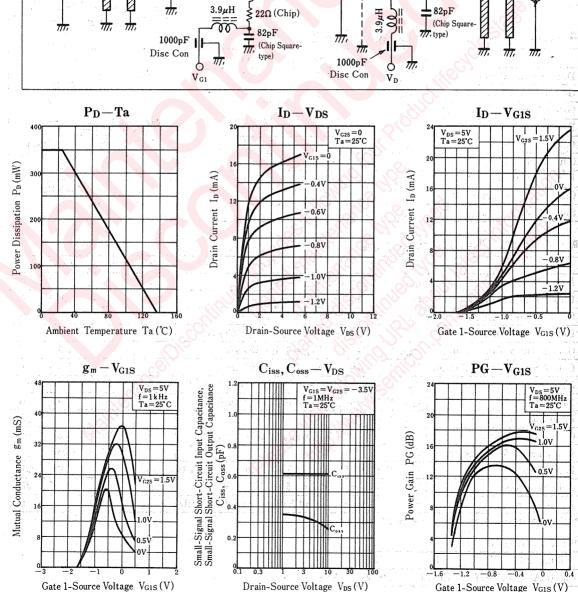
<sup>\*1</sup> Σnsert a serial resistor 33kΩ at Gate1 and Gate2, respectively.

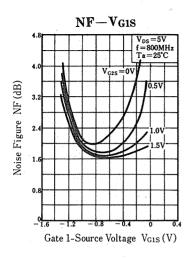
\*2 Ipss Ranking

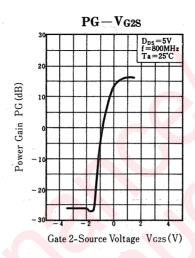
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Rank	P	Q	R	S
I <sub>DSS</sub> (mA)	8.5~17	15~21	19~30	25~35

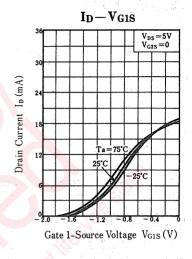
\*3 PG, NF Measuring Circuit (f=800MHz)











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